

REVERSE VOLTAGE: 50 to 600VOLTS
FORWARD CURRENT: 25.0 AMPERE

FEATURES

- Glass passivated chip junction
- Reliable low cost construction utilizing molded plastic technique
- Ideal for printed circuit board
- Low forward voltage drop
- Low reverse leakage current
- High surge current capability

MECHANICAL DATA

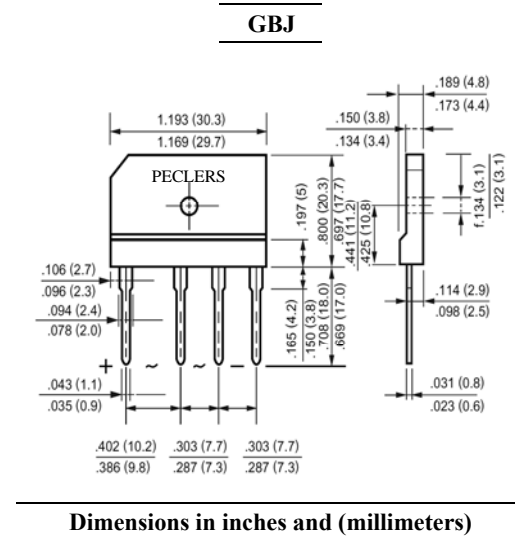
Case: Molded plastic, GBJ

Epoxy: UL 94V-O rate flame retardant

Terminals: Leads solderable per MIL-STD-202, method 208 guaranteed

Mounting position: Any

Weight: 0.23ounce, 6.6gram



Maximum Ratings and Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

	Symbols	GBJ25005L	GBJ2501L	GBJ2502L	GBJ2504L	GBJ2506L	Units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	Volts
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	Volts
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	Volts
Maximum Average Forward Rectified Current with Heatsink at $T_C=100^\circ\text{C}$	$I_{(AV)}$	25.0					Amp
Peak Forward Surge Current, 8.3ms single half-sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	300					Amp
Maximum Forward Voltage Drop per Element at 12.5A DC and 25°C	V_F	0.92					Volts
Maximum Reverse Current at $T_A=25^\circ\text{C}$ at Rated DC Blocking Voltage $T_A=125^\circ\text{C}$	I_R	10.0 500					uAmp
Typical Junction Capacitance (Note 1)	C_J	85					pF
Typical Thermal Resistance (Note 2)	$R_{\theta JC}$	0.6					°C/W
Operating and Storage Temperature Range	T_J, T_{stg}	-55 to +150					°C

NOTES:

1- Measured at 1 MHz and applied reverse voltage of 4.0 VDC.

2- Thermal Resistance fromn Junction to Case with Device Mounted on 300mm x 300mm x 1.6mmCu Plate Heatsink.

RATINGS AND CHARACTERISTIC CURVES

FIG.1 - FORWARD CURRENT DERATING CURVE

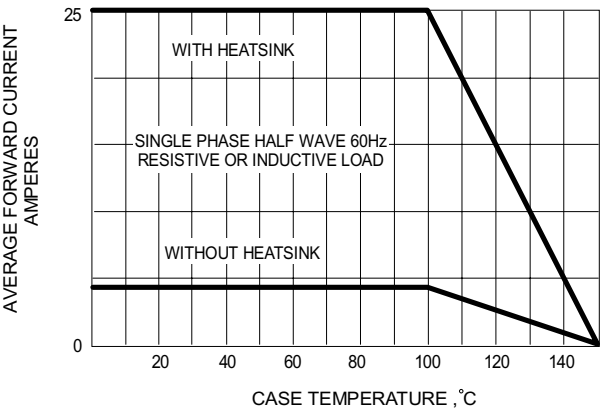


FIG.2 - MAXIMUM NON-REPETITIVE SURGE CURRENT

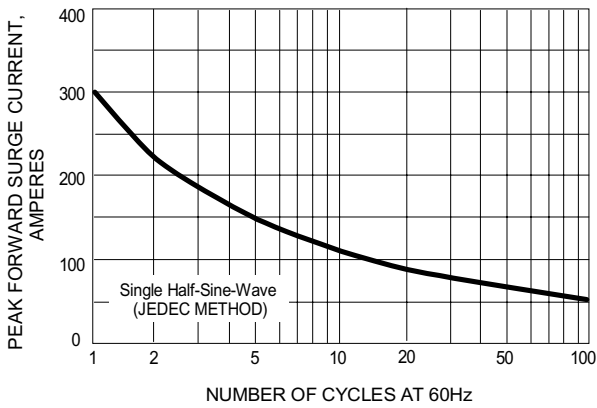


FIG.3-TYPICAL REVERSE CHARACTERISTICS

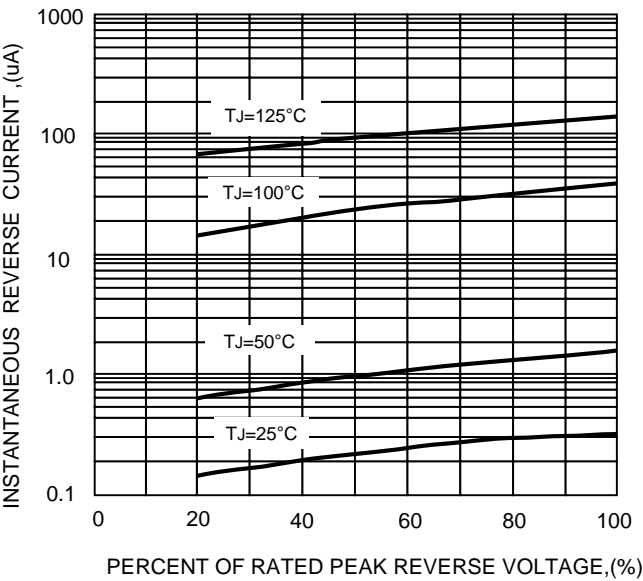


FIG.4-TYPICAL FORWARD CHARACTERISTICS

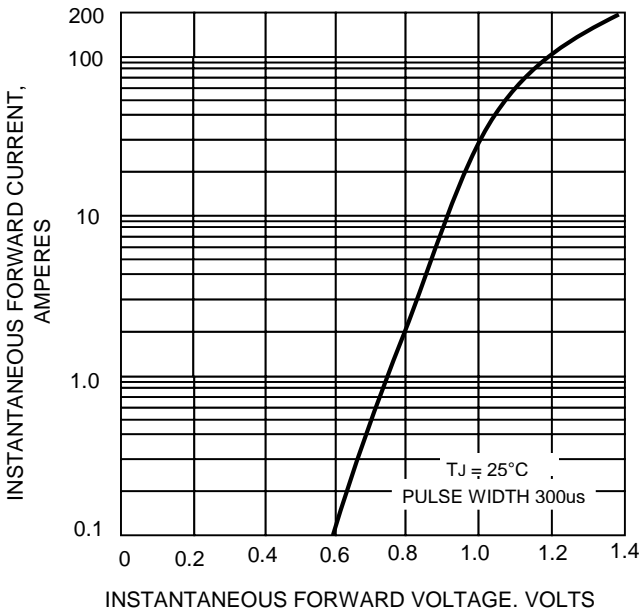


FIG.5-TYPICAL JUNCTION CAPACITANCE

